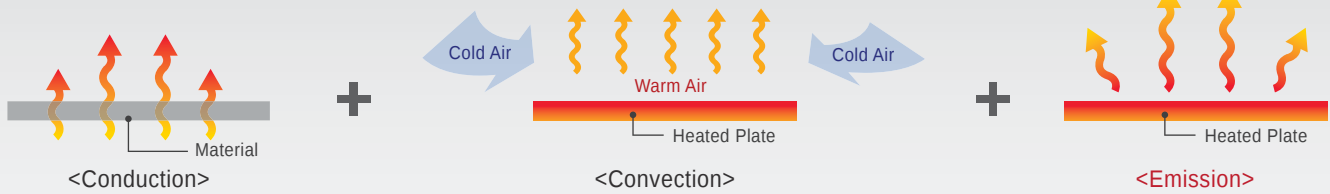


HTP Core Competence

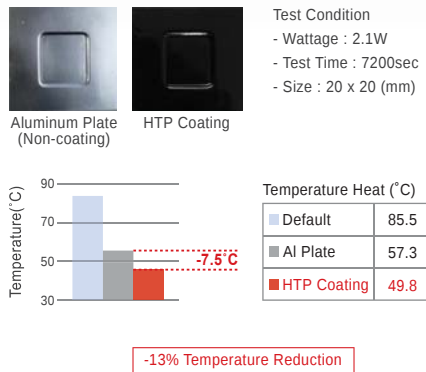


Radiant Heat Mechanism Improvement

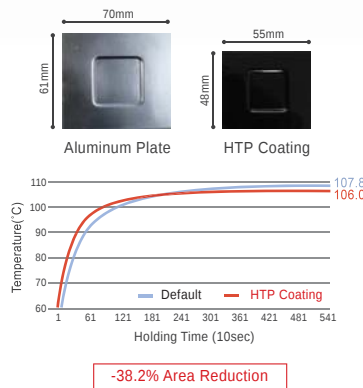


Design Merit & Advantages

Temperature Reducing Effect



Area Reduction Effect



Reflected Heat Distribution Map

TIM, PCM Flow Resistivity Reduction Design

Increasing Surface Area

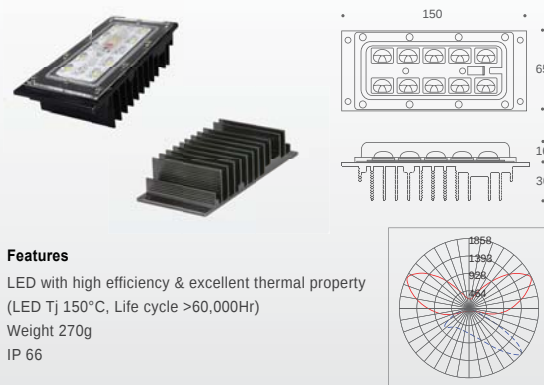
Design for Effective Heat Transfer of Radiation & Convection

Emissivity Maximize

Using High Emissivity Material and Surface Treatment

Application (HUD, Power Board, SMPS, LED Lamp, PCB Board, Heat Sink, Automotive Headlight)

A. LED Module (Heat Sink)



Ordering Information

	Consumed Wattage	Number of LEDs	Drive Current	Luminous Flux	CCT*
Amost-20-egd	21W	10	700mA	2388 lm	4500~5700K

B. PCB Board

Case 1. LED Metal PCB

Test Condition

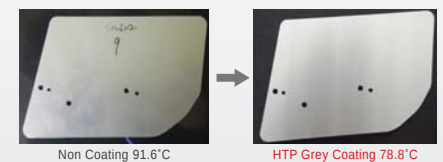
- Ambient Temp. : 25°C
- Test Time : 30hr



Case 2. LED Head Light PCB

Test Condition

- Ambient Temp. : 26.3°C
- Wattage : 12W



C. 72W LED Retrofit Lamp with Heat Sink Design

